



Features

- Very small size of 1206
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency recognition: UL, CSA, TUV

RELAYS

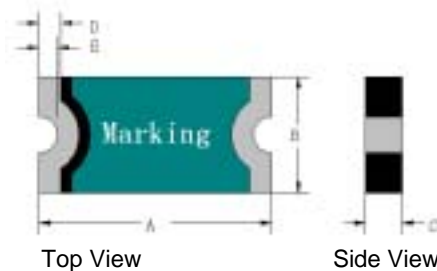


LP-NSM series

Surface-mount devices

Product Dimensions (mm) & Marking System

Part number	A	B	C	D	E	Part marking
	Max	Max	Max	Typ	Typ.	
LP-NSM012	3.50	1.80	0.75	0.60	0.20	P
LP-NSM016	3.50	1.80	0.80	0.60	0.20	T
LP-NSM020	3.50	1.80	0.80	0.60	0.20	C
LP-NSM035	3.50	1.80	0.85	0.60	0.20	W
LP-NSM050	3.50	1.80	0.85	0.60	0.20	A
LP-NSM075	3.50	1.80	1.30	0.60	0.20	Y
LP-NSM110	3.50	1.80	1.30	0.60	0.20	O
LP-NSM150	3.50	1.80	2.25	0.60	0.20	N



Electrical Characteristics

Part number	I_H	I_T	V_{max}	I_{max}	T_{trip}		Pd_{typ}	R_{min}	R_{1max}
	(A)	(A)	(V)	(A)	Current(A)	Time(S)	(W)	()	()
LP-NSM012	0.125	0.29	30	20	1.0	0.20	0.6	1.50	6.00
LP-NSM016	0.16	0.37	30	20	1.0	0.30	0.6	1.20	4.50
LP-NSM020	0.20	0.40	16	40	8.0	0.05	0.6	0.60	2.50
LP-NSM035	0.35	0.75	6	40	8.0	0.10	0.6	0.30	1.20
LP-NSM050	0.50	1.00	6	40	8.0	0.10	0.6	0.15	0.70
LP-NSM075	0.75	1.50	6	40	8.0	0.20	0.6	0.10	0.29
LP-NSM110	1.10	1.80	6	40	8.0	3.00	0.6	0.055	0.21
LP-NSM150	1.50	3.00	6	40	8.0	1.00	0.6	0.04	0.12

I_H =Hold current: maximum current at which the device will not trip at 25 °C still air.

I_T =Trip current: minimum current at which the device will always trip at 25 °C still air.

V_{max} =Maximum voltage device can withstand without damage at rated current.

I_{max} =Maximum fault current device can withstand without damage at rated voltage.

T_{trip} =Maximum time to trip(s) at assigned current.

R_{min} =Minimum device resistance at 25 °C prior to tripping.

R_{1max} =Maximum device resistance measured in the nontripped state 1 hour post reflow.

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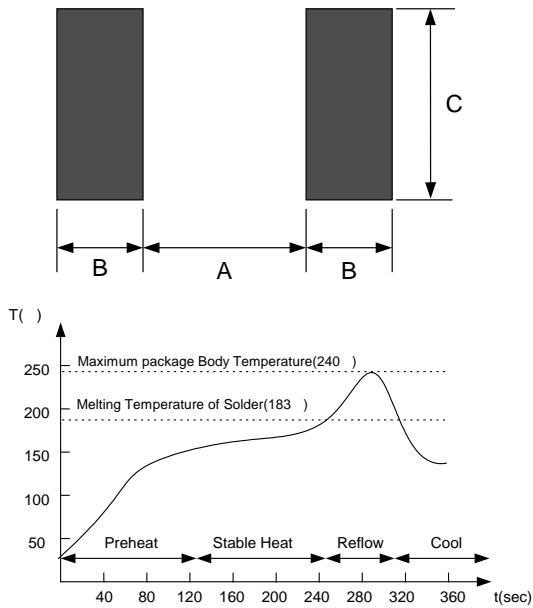
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[Http://www.way-on.com](http://www.way-on.com)

Test Procedures And Requirements

Test	Test Conditions	Accept/Reject Criteria
Resistance	In still air @ 25	R_{min} R R_{1max}
Time to Trip	Specified current, V_{max} , 25	T maximum Time to Trip
Hold Current	30min, at I_H	No trip
Trip Cycle Life	V_{max} , I_{max} , 100cycles	No arcing or burning
Trip Endurance	V_{max} , 24hours	No arcing or burning

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LP-NSM012	1.80	1.00	1.80
LP-NSM016	1.80	1.00	1.80
LP-NSM020	1.80	1.00	1.80
LP-NSM035	1.80	1.00	1.80
LP-NSM050	1.80	1.00	1.80
LP-NSM075	1.80	1.00	1.80
LP-NSM110	1.80	1.00	1.80
LP-NSM150	1.80	1.00	1.80

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape and Reel:

LP-NSM012~ LP-NSM050.....4000pcs per reel

LP-NSM075~ LP-NSM110.....3000pcs per reel

LP-NSM150.....2000pcs per reel